



## Product/Process Change Notice - PCN 12\_0226 Rev. -

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This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

**PCN Title:** Conversion of AD9943, AD9944, and AD9945 from Punched to Sawn Leadframe and Transfer of Backend Process to STATSChipPAC Malaysia

**Publication Date:** 14-Sep-2012

**Effectivity Date:** 13-Dec-2012 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Initial Release

### Description Of Change

Change Assembly Site from STATSChipPAC Singapore to STATSChipPAC Malaysia.  
Change Test Site from STATSChipPAC Singapore to STATSChipPAC Malaysia.  
Change Package outline from punch singulated outline to sawn singulated outline. See attached file.  
Change Bill of Material:  
-Mold Compound: from Sumitomo G700E to Sumitomo G770  
-Die Attach: from Ablestik 8290 to Ablestik 3230  
-Wire diameter: from 1.0mil to 0.8mil

### Reason For Change

Sawn LFCSP is ADI's technology direction for LFCSP. The use of ADI qualified SCM-Malaysia as an assembly and test site will ensure continued source of product supply. ADI's backend subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

### Impact of the change (positive or negative) on fit, form, function & reliability

The devices function and reliability as specified by the product datasheet will be unaffected by these changes. The foot print dimension will remain the same for both punch and sawn LFCSP packages.

### Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

### Supporting Documents

**Attachment 1: Type:** Package Outline Drawing

ADI\_PCN\_12\_0226\_Rev\_-\_POD\_comparison.pdf

**Attachment 2: Type:** Qualification Report Summary

**Attachment 3: Type:** Test Correlation Report

ADI\_PCN\_12\_0226\_Rev\_-\_AD9945\_43\_44 Test Product Transfer Qualification.pdf

**For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative**

**Americas:** [PCN\\_Americas@analog.com](mailto:PCN_Americas@analog.com)

**Europe:** [PCN\\_Europe@analog.com](mailto:PCN_Europe@analog.com)

**Japan:** [PCN\\_Japan@analog.com](mailto:PCN_Japan@analog.com)

**Rest of Asia:** [PCN\\_ROA@analog.com](mailto:PCN_ROA@analog.com)

**Appendix A - Affected ADI Models**

**Added Parts On This Revision - Product Family / Model Number (6)**

AD9943 / AD9943KCPZ	AD9943 / AD9943KCPZRL	AD9944 / AD9944KCPZ	AD9944 / AD9944KCPZRL	AD9945 / AD9945KCPZ
AD9945 / AD9945KCPZRL7				

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	14-Sep-2012	13-Dec-2012	Initial Release

Analog Devices, Inc.

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